

L Number	Hits	Search Text	DB	Time stamp
1	839	etch\$3 with rate? with (oxide? insulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:10
2	24	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:10
3	21	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon)) and @ad<19991015	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:13
4	0	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon)) with (slow\$2 fast\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:12
5	0	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon)) same trench\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:13
6	4	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon)) with stop\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:13
7	4	((etch\$3 with rate? with (oxide? insulat\$3)) with (polysilicon amorphous adj silicon)) with stop\$3) and @ad<19991015	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/27 15:13